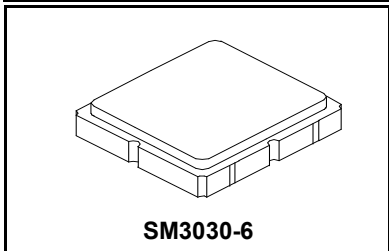


- Tape and Reel Standard per ANSI/EIA-481
- Moisture Sensitivity Level: 1

RoHS  
Compliant

SF2486E

2549.5 MHz  
SAW Filter



**Absolute Maximum Ratings**

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operable Temperature Range	-20 to +70	°C
Specification Temperature Range	-20 to +70	°C
Storage Temperature Range in Tape and Reel	-30 to +85	°C

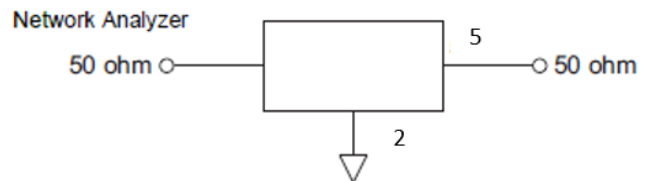
**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_c$			2549.5		MHz
Insertion Loss (2501 to 2598 MHz)	IL			2.8	4.0	dB
Amplitude Ripple (2501 to 2598 MHz)				1.7	2.5	dB
VSWR (2501 to 2598 MHz)				2.0	2.5	
Attenuation, reference level from 0 dB						dB
DC to 2400 MHz			25	28		
2400 to 2445 MHz			31	38		
2445 to 2460 MHz			22	29		
2660 to 3800 MHz			30	36		
3800 to 5000 MHz			15	20		
Temperature Coefficient of Frequency				-36		ppm/°C
Case Style	SMD 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	D7, YWWS					
Nominal Impedance	50Ω					

**Electrical Connections**

Connection	Terminals
Input	2
Output	5
Ground	All Others

**Measurement Circuit**

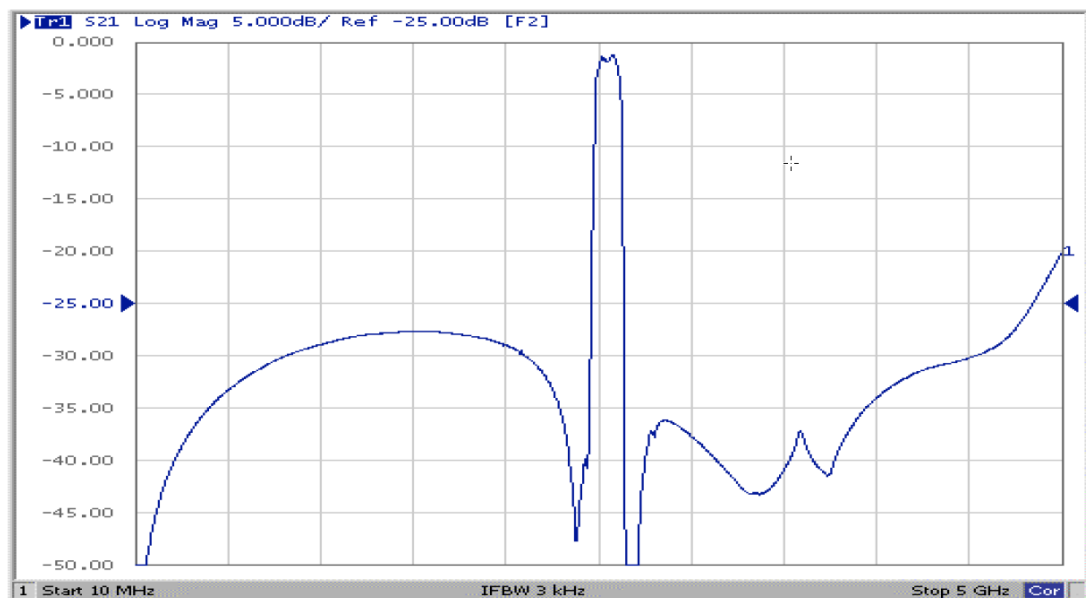
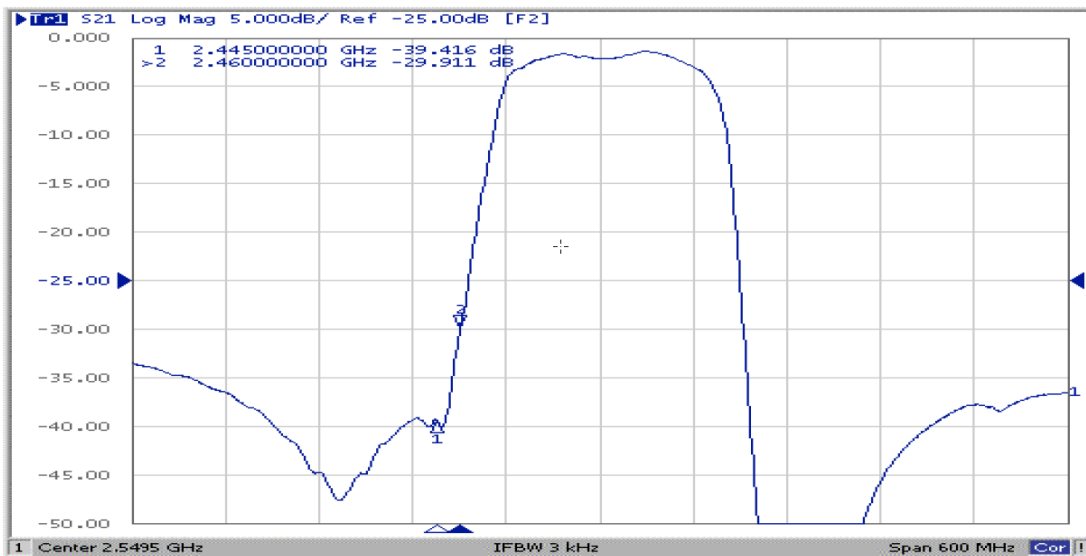
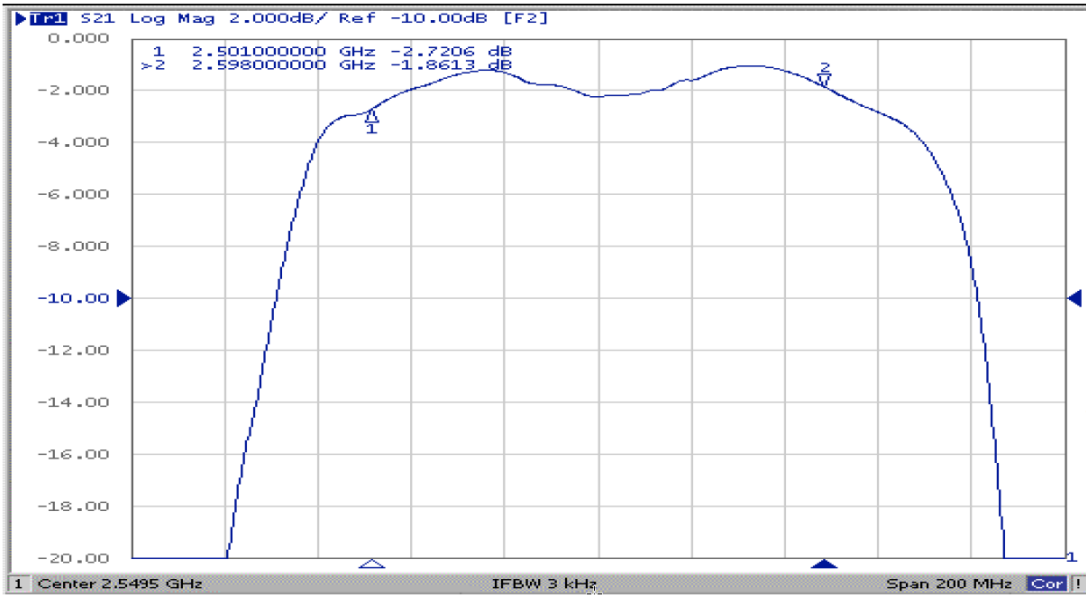


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

**NOTES:**

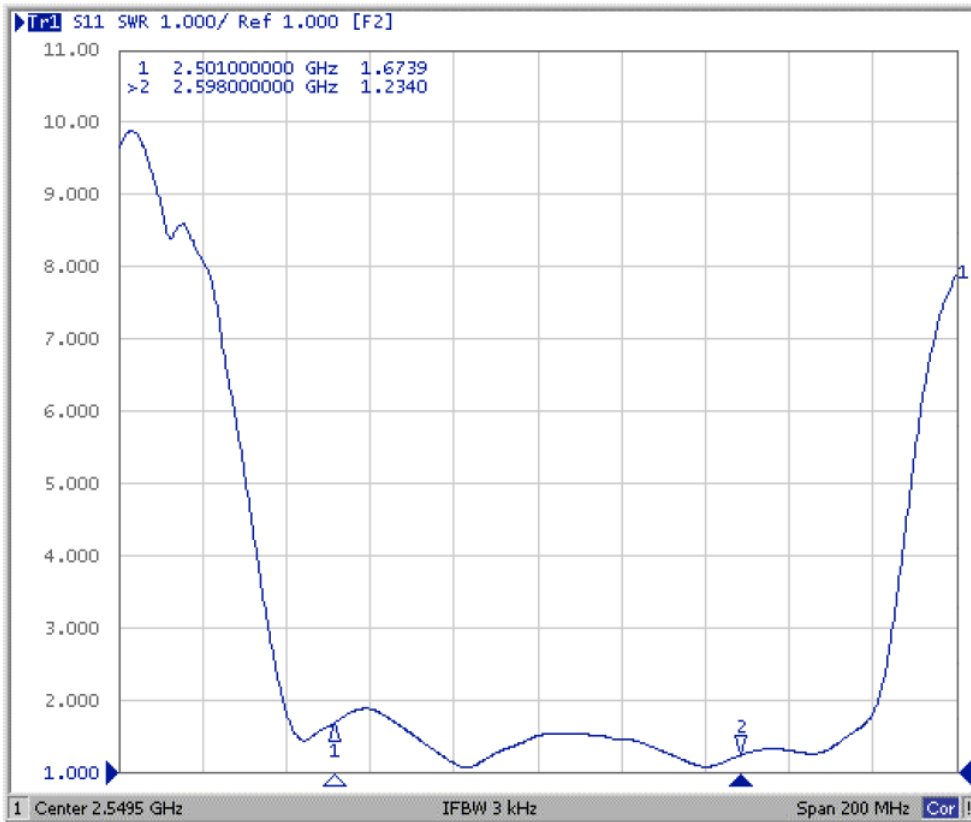
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

# Frequency Characteristics:

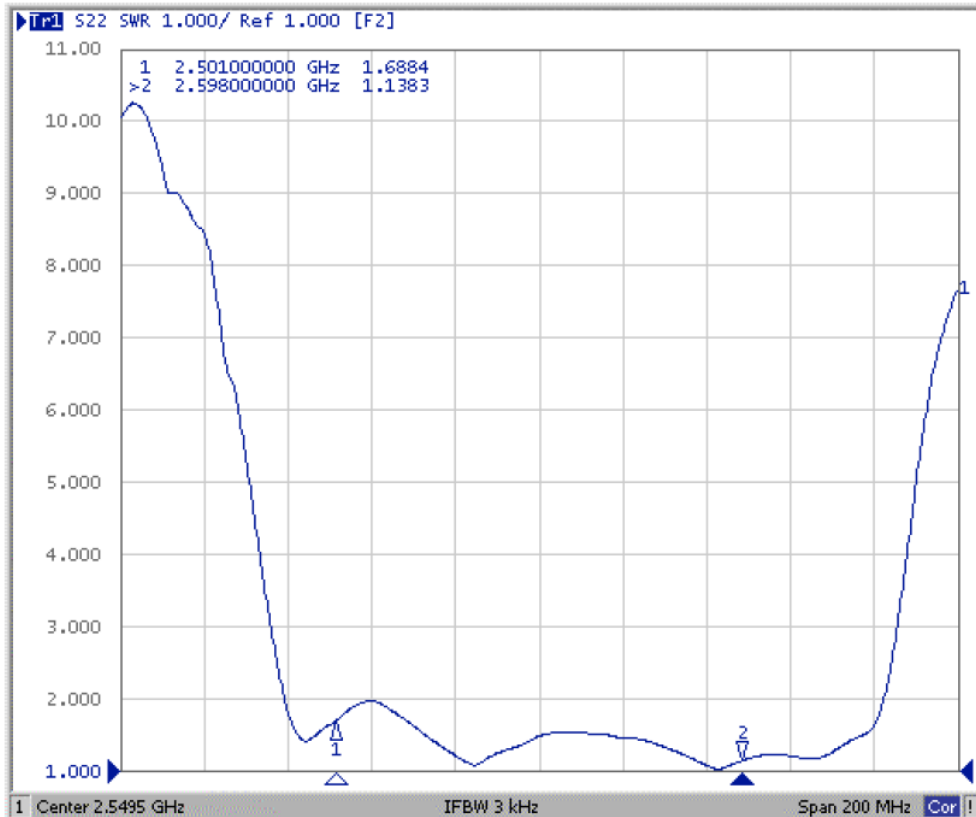


# Frequency Characteristics:

S11



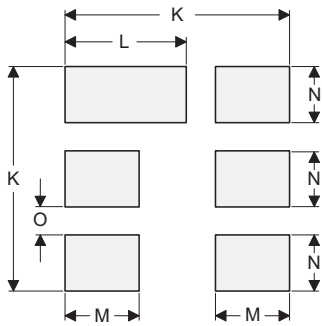
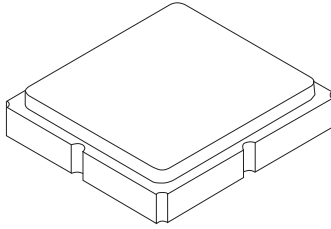
S22



# SM3030-6 Ceramic 6-Terminal Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint

## Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K	-	3.20	-	-	0.126	-
L	-	1.70	-	-	0.067	-
M	-	1.05	-	-	0.041	-
N	-	0.81	-	-	0.032	-
O	-	0.38	-	-	0.015	-
P	0.15	0.30	0.45	0.005	0.011	0.017
Q	0.07	0.20	0.36	0.002	0.007	0.014
R	0.62	0.7	0.78	0.024	0.027	0.030



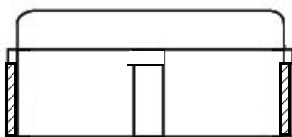
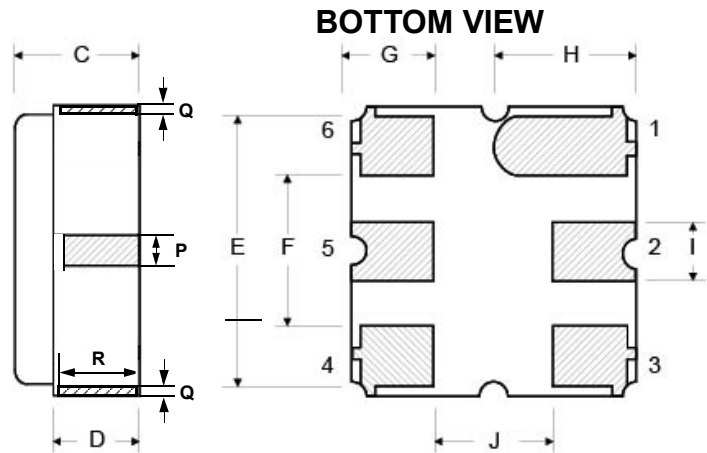
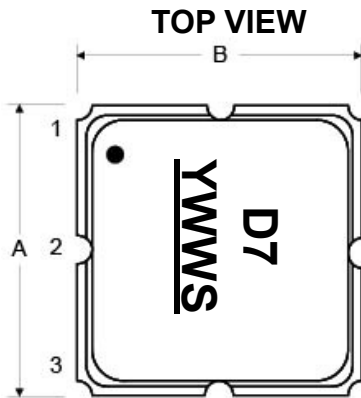
**PCB Footprint Top View**

## Case Materials

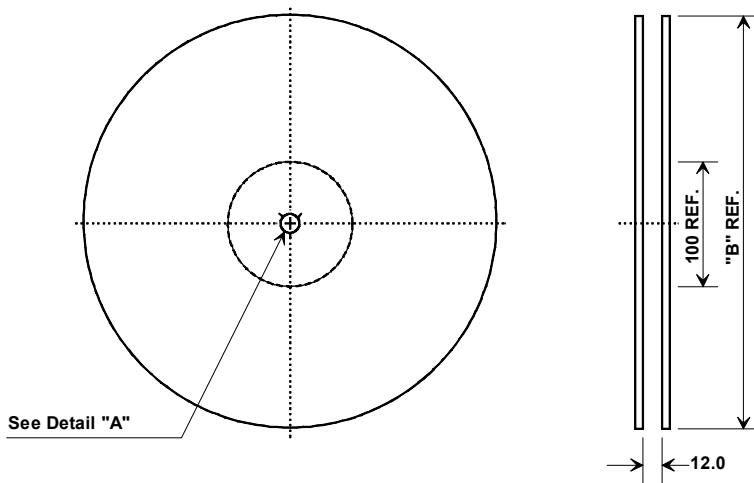
Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic

## Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others

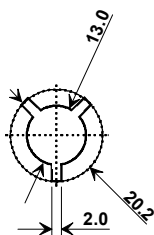


## Tape and Reel Specifications



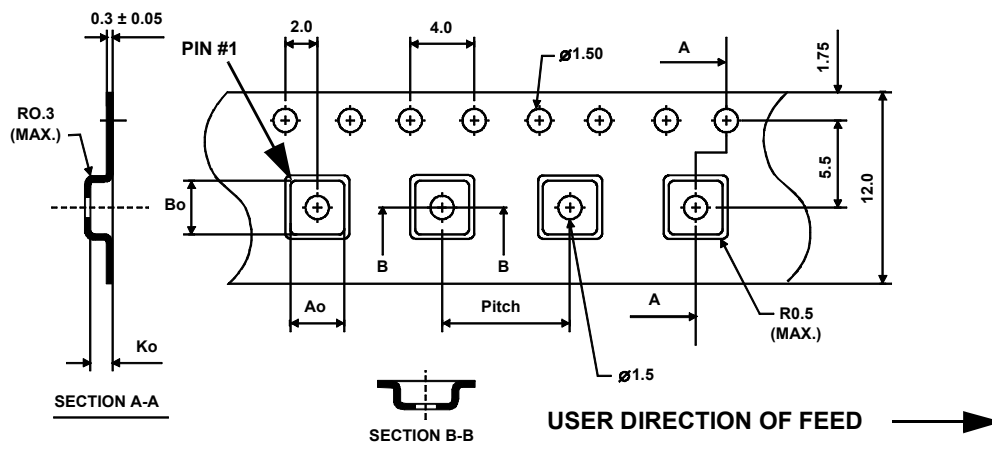
Tape and Reel Standard per ANSI/EIA-481

"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



## COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.3 mm
Bo	3.3 mm
Ko	1.4 mm
Pitch	8.0 mm
W	12.0 mm



## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (20~40 seconds).
4. Time: 2 times maximum.

